

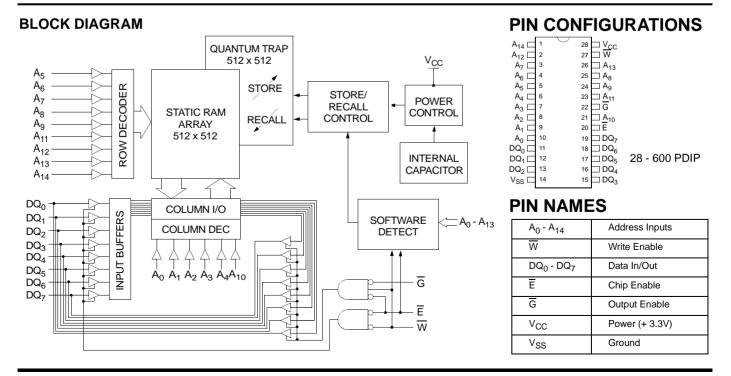
STK16C88-3 32K x 8 AutoStorePlus™ nvSRAM 3.3V QuantumTrap™ CMOS Nonvolatile Static RAM

FEATURES

- Transparent Data Save on Power Down
- Internal Capacitor Guarantees *AutoStore*™ Regardless of Power-Down Slew Rate
- Directly Replaces 32K x 8 Static RAM, Battery-Backed RAM or EEPROM
- 35 Access Time
- STORE to Nonvolatile Elements Initiated by Software or AutoStorePlus™
- *RECALL* to SRAM Initiated by Software or Power Restore
- 10mA Typical I_{cc} at 200ns Cycle Time
- Unlimited READ, WRITE and RECALL Cycles
- 1,000,000 STORE Cycles to Nonvolatile Elements (Commercial/Industrial)
- 100-Year Data Retention in nonvolatile elements (Commercial/Industrial)
- Single 3.3V <u>+</u> 0.3V Operation
- Commercial and Industrial Temperatures
- 28-Pin PDIP Package

DESCRIPTION

The STK16C88-3 is a fast SRAM with a nonvolatile element incorporated in each static memory cell. The SRAM can be read and written an unlimited number of times, while independent nonvolatile data resides in Nonvolatile Elements. Data transfers from the SRAM to the Nonvolatile Elements (the STORE operation) can take place automatically on power down. An internal capacitor guarantees the STORE operation regardless of power-down slew rate. Transfers from the Nonvolatile Elements to the SRAM (the RECALL operation) take place automatically on restoration of power. Initiation of STORE and RECALL cycles can also be controlled by entering control sequences on the SRAM inputs. The STK16C88-3 is pin-compatible with 32k x 8 SRAMs and battery-backed SRAMs, allowing direct substitution while providing superior performance. The STK14C88-3, which uses an external capacitor, is also available.



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STK16C88-3_ **ABSOLUTE MAXIMUM RATINGS**^a

Voltage on Input Relative to Ground	–0.5V to 4.5V
Voltage on Input Relative to V _{SS}	-0.6V to (V _{CC} + 0.5V)
Voltage on DQ ₀₋₇	-0.5V to (V _{CC} + 0.5V)
Temperature under Bias	–55°C to 125°C
Storage Temperature	–65°C to 150°C
Power Dissipation	1W
DC Output Current (1 output at a time, 1s dura	ation)

Note a: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

$(V_{CC} = 3.0V - 3.6V)$

DC CHARACTERISTICS

SYMBOL	PARAMETER	СОММ	ERCIAL	INDUS	STRIAL	UNITS	NOTES
STNBOL	PARAMETER	MIN	MAX	MIN	MAX	UNITS	NOTES
I _{CC1} b	Average V _{CC} Current		50		52	mA	t _{AVAV} = 35ns
I _{CC2} c	Average V _{CC} Current during STORE		3		3	mA	All Inputs Don't Care, V _{CC} = max
I _{CC3} b	Average V _{CC} Current at t _{AVAV} = 200ns 3.3V, 25°C, Typical		8		8	mA	$\overline{W} \ge (V_{CC} - 0.2V)$ All Others Cycling, CMOS Levels
I _{SB1} ^d	Average V _{CC} Current (Standby, Cycling TTL Input Levels)		18		19	mA	t_{AVAV} = 35ns, $\overline{E} \ge V_{IH}$
I _{SB2} d	V _{CC} Standby Current (Standby, Stable CMOS Input Levels)		1		1	mA	$\label{eq:constraint} \begin{split} \overline{E} &\geq (V_{CC} - 0.2V) \\ \text{All Others } V_{IN} &\leq 0.2V \text{ or } \geq (V_{CC} - 0.2V) \end{split}$
I _{ILK}	Input Leakage Current		±1		±1	μΑ	V _{CC} = max V _{IN} = V _{SS} to V _{CC}
I _{OLK}	Off-State Output Leakage Current		±1		±1	μA	$V_{CC} = max$ $V_{IN} = V_{SS}$ to V_{CC} , \overline{E} or $\overline{G} \ge V_{IH}$
VIH	Input Logic "1" Voltage	2.2	V _{CC} + .5	2.2	V _{CC} + .5	V	All Inputs
V _{IL}	Input Logic "0" Voltage	V _{SS} – .5	0.8	V _{SS} – .5	0.8	V	All Inputs
V _{OH}	Output Logic "1" Voltage	2.4		2.4		V	I _{OUT} =-4mA
V _{OL}	Output Logic "0" Voltage		0.4		0.4	V	I _{OUT} = 8mA
T _A	Operating Temperature	0	70	-40	85	°C	

Note b: I_{CC_1} and I_{CC_3} are dependent on output loading and cycle rate. The specified values are obtained with outputs unloaded. Note c: I_{CC_2} and I_{CC_4} are the average currents required for the duration of the respective *STORE* cycles (t_{STORE}).

Note d: $\vec{E} \ge V_{|H|}$ will not produce standby current levels until any nonvolatile cycle in progress has timed out.

AC TEST CONDITIONS

Input Pulse Levels
Input Rise and Fall Times $\ldots \le 5$ ns
Input and Output Timing Reference Levels
Output Load See Figure 1

CAPACITANCE^e $(T_A = 25^{\circ}C, f = 1.0MHz)$

SYMBOL	BOL PARAMETER		UNITS	CONDITIONS
C _{IN}	Input Capacitance	5	pF	$\Delta V = 0$ to $3V$
C _{OUT}	Output Capacitance	7	pF	$\Delta V = 0$ to 3V

Note e: These parameters are guaranteed but not tested.

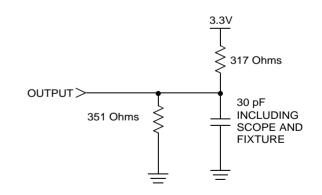


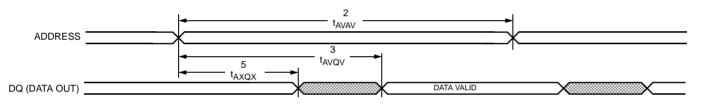
Figure 1: AC Output Loading

 $(V_{CC} = 3.0V-3.6V)$

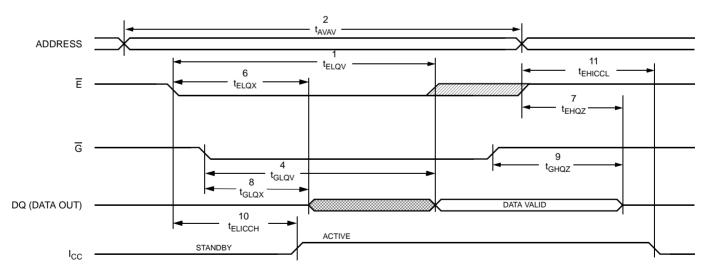
SRAM READ CYCLES #1 & #2

SYME	SYMBOLS		STK16C88-3-35		
#1, #2	Alt.	PARAMETER	MIN		UNITS
^t ELQV	t _{ACS}	Chip Enable Access Time		35	ns
t _{AVAV} f	t _{RC}	Read Cycle Time	35		ns
t _{AVQV} g	t _{AA}	Address Access Time		35	ns
t _{GLQV}	t _{OE}	Output Enable to Data Valid		15	ns
t _{AXQX} g	tон	Output Hold after Address Change	5		ns
t _{ELQX}	t _{LZ}	Chip Enable to Output Active	5		ns
t _{EHQZ} h	t _{HZ}	Chip Disable to Output Inactive		13	ns
t _{GLQX}	tOLZ	Output Enable to Output Active	0		ns
t _{GHQZ} h	t _{OHZ}	Output Disable to Output Inactive		13	ns
t _{ELICCH} e	t _{PA}	Chip Enable to Power Active	0		ns
^t EHICCL ^{d, e}	t _{PS}	Chip Disable to Power Standby		35	ns
	#1, #2 tELQV tAVAV ^f tAVQV ^g tGLQV tAXQX ^g tELQX tEHQZ ^h tGLQX tGLQX tGLQX tGLQX tGLQX tGLQX tGLQX tGLQX tGLQX tGLQX	#1, #2 Alt. tELQV tACS tAVAV ^f tRC tAVAV ^f tAA tGLQV tOE tELQX tLZ tELQX tHZ tGLQX tOLZ tGHQZ ^h tOHZ tELICCH ^e tPA	#1, #2Alt.PARAMETER t_{ELQV} t_{ACS} Chip Enable Access Time t_{AVAV}^f t_{RC} Read Cycle Time t_{AVQV}^g t_{AA} Address Access Time t_{AVQV}^g t_{AA} Address Access Time t_{GLQV} t_{OE} Output Enable to Data Valid t_{AXQX}^g t_{OH} Output Hold after Address Change t_{ELQX} t_{LZ} Chip Enable to Output Active t_{ELQX}^h t_{HZ} Chip Disable to Output Active t_{GLQX}^h t_{OLZ} Output Enable to Output Active t_{GHQZ}^h t_{OHZ} Output Disable to Output Inactive t_{ELICCH}^e t_{PA} Chip Enable to Power Active	#1, #2Alt.PARAMETER t_{ELQV} t_{ACS} Chip Enable Access TimeImage: constraint of the state of	#1, #2Alt.MINMAX t_{ELQV} t_{ACS} Chip Enable Access Time

SRAM READ CYCLE #1: Address Controlled^{f, g}



SRAM READ CYCLE #2: E Controlled



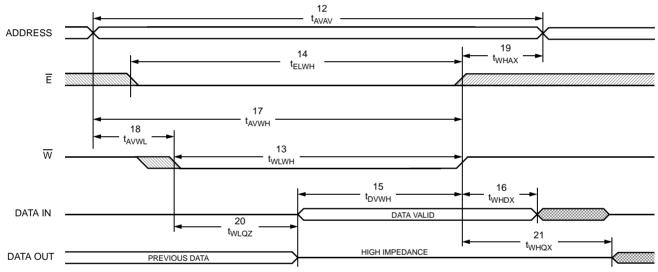
SRAM WRITE CYCLES #1 & #2

$(V_{CC} = 3.0V-3.6V)$

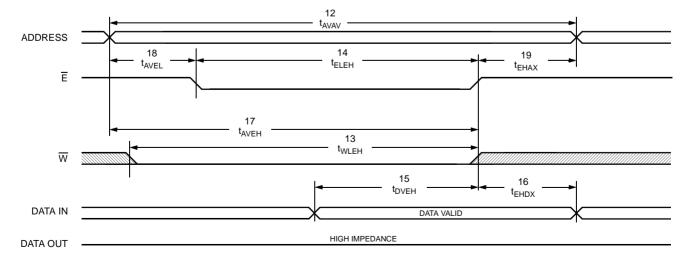
	SYMBOLS				STK16C88-3-35		
NO.	#1	#2	Alt.	PARAMETER	MIN	MAX	UNITS
12	t _{AVAV}	t _{AVAV}	t _{WC}	Write Cycle Time	35		ns
13	t _{WLWH}	t _{WLEH}	t _{WP}	Write Pulse Width	25		ns
14	t _{ELWH}	t _{ELEH}	t _{CW}	Chip Enable to End of Write	25		ns
15	t _{DVWH}	t _{DVEH}	t _{DW}	Data Set-up to End of Write	12		ns
16	t _{WHDX}	t _{EHDX}	t _{DH}	Data Hold after End of Write	0		ns
17	t _{AVWH}	t _{AVEH}	t _{AW}	Address Set-up to End of Write	25		ns
18	t _{AVWL}	t _{AVEL}	t _{AS}	Address Set-up to Start of Write	0		ns
19	t _{WHAX}	t _{EHAX}	t _{WR}	Address Hold after End of Write	0		ns
20	t _{WLQZ} ^{h, i}		t _{WZ}	Write Enable to Output Disable		13	ns
21	t _{WHQX}		t _{OW}	Output Active after End of Write	5		ns

Note i: If \overline{W} is low when \overline{E} goes low, the outputs remain in the high-impedance state. Note j: \overline{E} or \overline{W} must be $\ge V_{IH}$ during address transitions.

SRAM WRITE CYCLE #1: W Controlled



SRAM WRITE CYCLE #2: E Controlled



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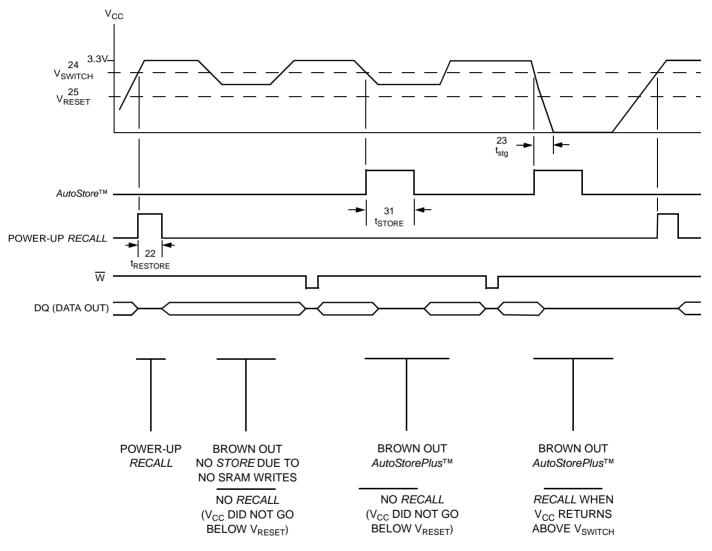
 $(V_{CC} = 3.0V - 3.6V)$

AutoStorePlus™/POWER-UP RECALL

-			• •	50		
NO.	SYMBOLS	PARAMETER	STK16	C88-3		NOTES
NU.	Standard	FARAWEIER	MIN	MAX	UNITS	NUTES
22	^t RESTORE	Power-up RECALL Duration		550	μs	k
23	t _{stg}	Minimum V_{CC} Slew Time to Ground	500		ns	e, g
24	V _{SWITCH}	Low Voltage Trigger Level	2.7	2.95	V	
25	V _{RESET}	Low Voltage Reset Level		2.4	V	е

Note k: $t_{RESTORE}$ starts from the time V_{CC} rises above V_{SWITCH} .

AutoStorePlus™/POWER-UP RECALL



SOFTWARE STORE/RECALL MODE SELECTION

Ē	w	\mathbf{A}_{13} - \mathbf{A}_0 (hex)	MODE	I/O	NOTES
L	н	0E38 31C7 03E0 3C1F 303F 0FC0	Read SRAM Read SRAM Read SRAM Read SRAM Read SRAM Nonvolatile <i>STORE</i>	Output Data Output Data Output Data Output Data Output Data Output High Z	l, m
L	н	0E38 31C7 03E0 3C1F 303F 0C63	Read SRAM Read SRAM Read SRAM Read SRAM Read SRAM Nonvolatile <i>RECALL</i>	Output Data Output Data Output Data Output Data Output Data Output High Z	l, m

Note I: The six consecutive addresses must be in the order listed. \overline{W} must be high during all six consecutive cycles to enable a nonvolatile cycle. Note m: While there are 15 addresses on the STK16C88-3, only the lower 14 are used to control software modes.

SOFTWARE STORE/RECALL CYCLE^{n, o}

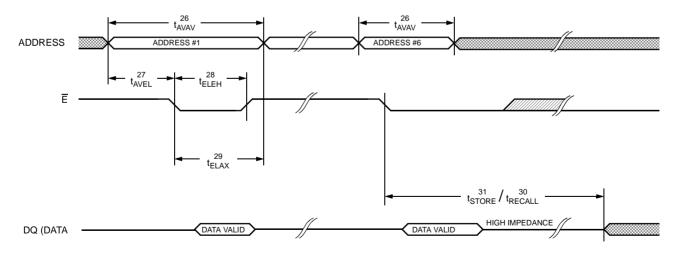
$(V_{CC} = 3.0V-3.6V)$

NO.		MBOLS PARAMETER -	STK160	UNITS	
NO.	STMBOLS		MIN	МАХ	UNITS
26	t _{AVAV}	STORE/RECALL Initiation Cycle Time	35		ns
27	t _{AVEL} n	Address Set-up Time	0		ns
28	t _{ELEH} n	Clock Pulse Width	25		ns
29	t _{ELAX} g, n	Address Hold Time	20		ns
30	^t RECALL	RECALL Cycle Duration		20	μs
31	^t STORE	STORE Cycle Duration		10	ms

Note n: The software sequence is clocked with \overline{E} controlled reads.

Note o: The six consecutive addresses must be in the order listed in the Software STORE/RECALL Mode Selection Table: (0E38, 31C7, 03E0, 3C1F, 303F, 0FC0) for a STORE cycle or (0E38, 31C7, 03E0, 3C1F, 303F, 0C63) for a RECALL cycle. W must be high during all six consecutive cycles.

SOFTWARE STORE/RECALL CYCLE: E Controlled^o



DEVICE OPERATION

The AutoStorePlusTM STK16C88-3 is a fast 32K x 8 SRAM that does not lose its data on power-down. The data is preserved in integral *QuantumTrapTM* Nonvolatile Elements while power is unavailable. The nonvolatility of the STK16C88-3 does not require any system intervention or support: *AutoStorePlusTM* on power-down and automatic RECALL on power-up guarantee data integrity without the use of batteries.

NOISE CONSIDERATIONS

Note that the STK16C88-3 is a high-speed memory and so must have a high-frequency bypass capacitor of approximately 0.1 μ F connected between V_{CC} and V_{SS}, using leads and traces that are as short as possible. As with all high-speed CMOS ICs, normal careful routing of power, ground and signals will help prevent noise problems.

SRAM READ

The STK16C88-3 performs a READ cycle whenever E and G are low and W is high. The address specified on pins $A_{0.14}$ determines which of the 32,768 data bytes will be accessed. When the READ is initiated by an address transition, the outputs will be valid after a delay of t_{AVQV} (READ cycle #1). If the READ is initiated by E or G, the outputs will be valid at t_{ELQV} or at t_{GLQV} , whichever is later (READ cycle #2). The data outputs will repeatedly respond to address changes within the t_{AVQV} access time without the need for transitions on any control input pins, and will remain valid until another address change or until E or G is brought high.

SRAM WRITE

A WRITE cycle is performed whenever E and \overline{W} are low. The address inputs must be stable prior to entering the WRITE cycle and must remain stable until either E or \overline{W} goes high at the end of the cycle. The data on the common I/O pins DQ₀₋₇ will be written into the memory if it is valid t_{DVWH} before the end of a \overline{W} controlled WRITE or t_{DVEH} before the end of an E controlled WRITE.

It is recommended that \overline{G} be kept high during the entire WRITE cycle to avoid data bus contention on the common I/O lines. If \overline{G} is left low, internal circuitry will turn off the output buffers t_{WLQZ} after \overline{W} goes low.

AutoStorePlus[™] OPERATION

The STK16C88-3's automatic *STORE* on powerdown is completely transparent to the system. The *AutoStore*TM initiation takes less than 500ns when power is lost (V_{CC} < V_{SWITCH}) at which point the part depends only on its internal capacitor for *STORE* completion. If the power supply drops faster than 20µs/volt before Vccx reaches Vswitch, then a 2.2 ohm resistor should be inserted between Vccx and the system supply to avoid a momentary excess of current between Vccx and Vcap.

In order to prevent unneeded *STORE* operations, automatic *STORE*s will be ignored unless at least one WRITE operation has taken place since the most recent *STORE* or *RECALL* cycle. Software-initiated *STORE* cycles are performed regardless of whether or not a WRITE operation has taken place.

POWER-UP RECALL

During power up, or after any low-power condition ($V_{CC} < V_{RESET}$), an internal *RECALL* request will be latched. When V_{CC} once again exceeds the sense voltage of V_{SWITCH} , a *RECALL* cycle will automatically be initiated and will take $t_{RESTORE}$ to complete.

If the STK16C88-3 is in a WRITE state at the end of power-up *RECALL*, the SRAM data will be corrupted. To help avoid this situation, a $10k\Omega$ resistor should be connected either between W and system V_{cc} or between E and system V_{cc}.

SOFTWARE NONVOLATILE STORE

The STK16C88-3 software *STORE* cycle is initiated by executing sequential READ cycles from six specific address locations. During the *STORE* cycle an erase of the previous nonvolatile data is first performed, followed by a program of the nonvolatile elements. The program operation copies the SRAM data into nonvolatile memory. Once a *STORE* cycle is initiated, further input and output are disabled until the cycle is completed.

Because a sequence of READs from specific addresses is used for *STORE* initiation, it is important that no other READ or WRITE accesses intervene in the sequence or the sequence will be aborted and no *STORE* or *RECALL* will take place.

STK16C88-3

To initiate the software *STORE* cycle, the following READ sequence must be performed:

1.	Read address	0E38 (hex)	Valid READ
2.	Read address	31C7 (hex)	Valid READ
3.	Read address	03E0 (hex)	Valid READ
4.	Read address	3C1F (hex)	Valid READ
5.	Read address	303F (hex)	Valid READ
6.	Read address	0FC0 (hex)	Initiate STORE cycle

The software sequence must be clocked with E controlled READs.

Once the sixth address in the sequence has been entered, the *STORE* cycle will commence and the chip will be disabled. It is important that READ cycles and not WRITE cycles be used in the sequence, although it is not necessary that G be low for the sequence to be valid. After the t_{STORE} cycle time has been fulfilled, the SRAM will again be activated for READ and WRITE operation.

SOFTWARE NONVOLATILE RECALL

A software *RECALL* cycle is initiated with a sequence of READ operations in a manner similar to the software *STORE* initiation. To initiate the *RECALL* cycle, the following sequence of READ operations must be performed:

1.	Read address	0E38 (hex)	Valid READ
2.	Read address	31C7 (hex)	Valid READ
3.	Read address	03E0 (hex)	Valid READ
4.	Read address	3C1F (hex)	Valid READ
5.	Read address	303F (hex)	Valid READ
6.	Read address	0C63 (hex)	Initiate RECALL cycle

Internally, *RECALL* is a two-step procedure. First, the SRAM data is cleared, and second, the nonvola-

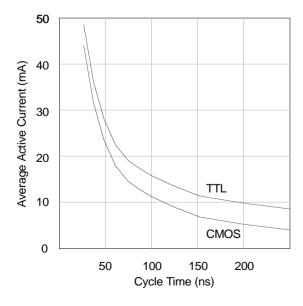


Figure 2: I_{CC} (max) Reads

tile information is transferred into the SRAM cells. After the t_{RECALL} cycle time the SRAM will once again be ready for READ and WRITE operations. The *RECALL* operation in no way alters the data in the Nonvolatile Elements. The nonvolatile data can be recalled an unlimited number of times.

HARDWARE PROTECT

The STK16C88-3 offers hardware protection against inadvertent *STORE* operation and SRAM WRITES during low-voltage conditions. When $V_{CC} < V_{SWITCH}$, all software *STORE* operations and SRAM WRITES are inhibited.

LOW AVERAGE ACTIVE POWER

The STK16C88-3 draws significantly less current when it is cycled at times longer than 55ns. Figure 2 shows the relationship between I_{cc} and READ cycle time. Worst-case current consumption is shown for both CMOS and TTL input levels (commercial temperature range, V_{cc} = 3.6V, 100% duty cycle on chip enable). Figure 3 shows the same relationship for WRITE cycles. If the chip enable duty cycle is less than 100%, only standby current is drawn when the chip is disabled. The overall average current drawn by the STK16C88-3 depends on the following items: 1) CMOS vs. TTL input levels; 2) the duty cycle of chip enable; 3) the overall cycle rate for accesses; 4) the ratio of READs to WRITES; 5) the operating temperature; 6) the V_{cc} level; and 7) I/ O loading.

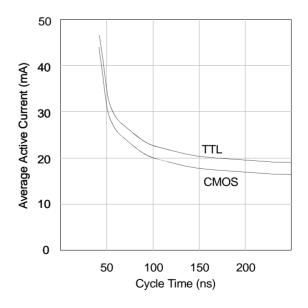
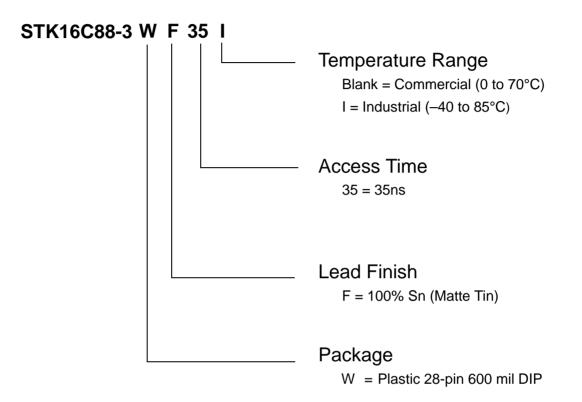


Figure 3: I_{CC} (max) Writes

ORDERING INFORMATION



Document Revision History

Revision	Date	Summary
0.0	December 2002	
0.1	September 2003	Added lead-free lead finish
0.2	March 2006	Removed 45ns and 55ns speed grades, Removed Leaded lead finish.